

Flexible

Moisture Resistant High Green Strength Electrically Conductive Epoxy Paste Adhesive

IDEAL FOR:

"Low" Bleeding

Large Area Die Attach

Screen-Printable

Component Attach

Substate Attach

DESCRIPTION:

ME8850-DA is designed for fine needle dispensing and screen-printing processing. This silver filled conductive die-attach adhesive can be rapidly cured at low temperatures. This single component, silver filled paste is ambient storable and electrically and thermally conductive. It is highly thixotropic with minimal sag.

ME8850-DA has been designed to eliminate bleeding on both silver plated copper and alloy 42 leadframes.

AVAILABILITY:

ME8850-DA is available in syringes or in jars.

APPLICATION PROCEDURES:

- (1) Thaw for 30 min. before opening jar or using syringes.
- (2) Dispense adhesive onto clean substrate with a suitable pattern to
- (3) Prebake at 80 C for 30 minutes
- (4) Cure according to the recommended schedules.

FLEXIBLE DIE ATTACH ME8850-DA

TYPICAL PROPERTIES*

Electrical Resistivity <5x10⁻⁴ ohm-cm (150 °C/ 5 minutes)

Dielectric Strength (Volts/mil)
Glass Transition Temp.(°C)
Current Carrying Capabilities
Lap-Shear Strength
N/A
Not Applicable
-20/-50 Minor
50 Amp/mm²
N/A

Device Push-off Strength >1000 psi

>6.9 N/mm²

Hardness (Type) 85 (A)
Cured Density (gm/cc) 3.8

Thermal Conductivity >55 Btu-in/hr-ft²-°F

>7.9 W/m-°C

Linear Thermal Expansion 100

Coeff. (ppm/°C)

Maximum Continuous 150

Operation Temp. (°C)

Avg. Viscosity(5.0 rpm, 24°C) 10,000 cp

(Brookfield DV-1,spindle CP51)

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CURE SCHEDULES:

<u>l'emperature</u>	<u>l ime</u>	Presure
100°C	2 hr	
125°C	1 hr	
150°C	30 min	

Pot life: 25°C for 3 days.

1 cP = 10-3 Pa·s = 1 mPa·s; 145psi=.99974MPa=.99974 N*mm²; 1lb = 4.448N; 1 inch=25.4 mm; 1V/mil=39.3701 V/mm; 1 lb-in = 0.11298 N-m

SHELF LIFE:

Storage temperature	Shelf Life
-40°C	1 yr
-20°C	3 mo
25°C	7 day

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PRODUCT DATA SHEET REV. B @ 12/09/03

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